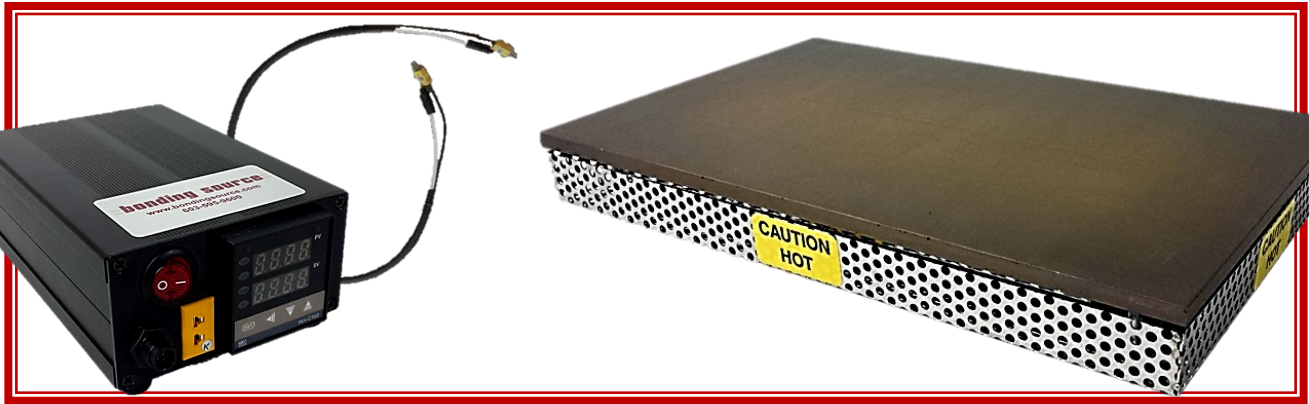


# **Bonding Source Hot Plates**

The microelectronics and RF/Microwave assemblers' choice for pre-tacking epoxy film, epoxy curing, SMD reflow, rework, and wire bonding base heat.

# **BS-6.5-10.5**

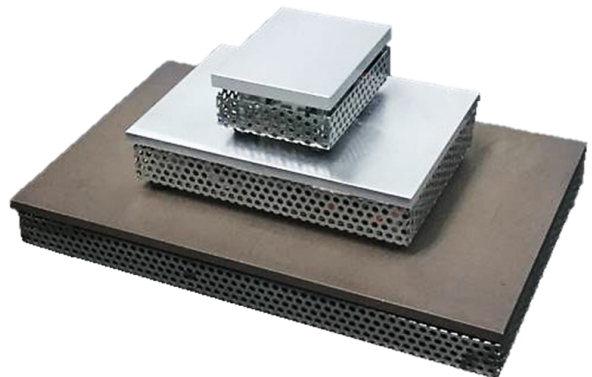


## **Hot Plate System Features**

- Expanded surface area for larger housings and PCBA's
- Low-profile (1.4" Ht.) hot plate conveniently fits beneath microscopes and wire bond stages
- Modular design: plates can be used interchangeably with Bonding Source digital PID controllers and cable assemblies
- Hot plates are matched in height to 1.4" and available in the following sizes: 10.5"x6.5", 6"x4", and 3"x2.5"
- Digital controller ensures process consistency
- Rapid heating and recovery

## **Technical Specifications**

<b>Overall Dimensions</b>		
• Length		10.5 in
• Width		6.5 in
• Height		1.4 in
Heated Area		10.5in x 6.5in
Weight		2.6 lbs
Max. Temperature		300 °C
Plate Material		Aluminum (Anodized)
Power Req.	120VAC	60Hz
Thermocouple Cable Length		3 ft
Power Cord Length		6 ft



# **bonding source**

Bonding Source  
603.595.9600  
One Perimeter Road  
Manchester NH 03103  
[www.bondingsource.com](http://www.bondingsource.com)